FIG.

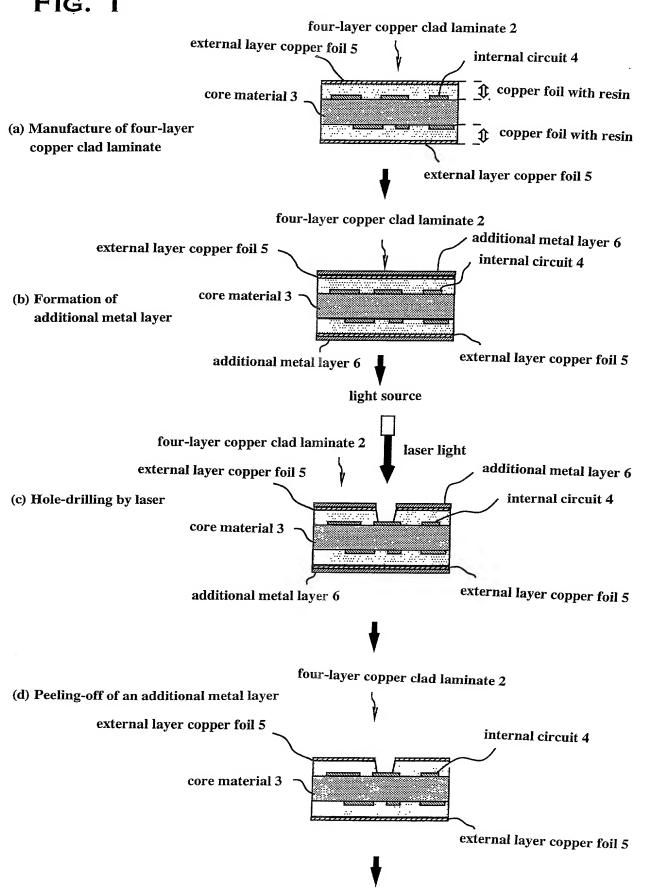
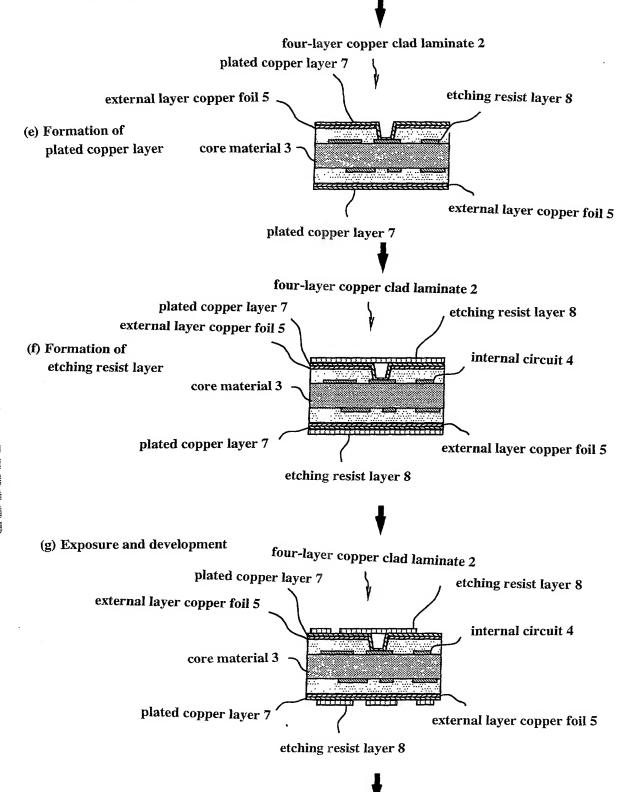
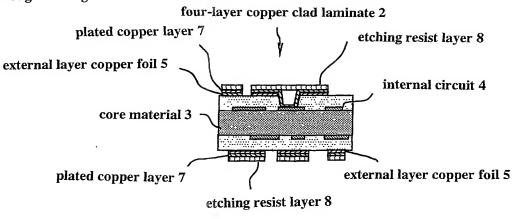
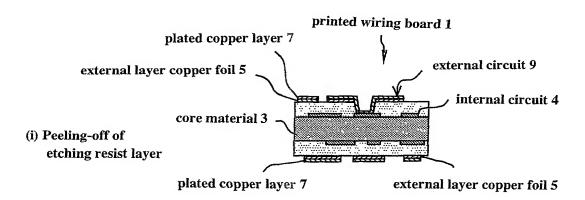


Fig. 2

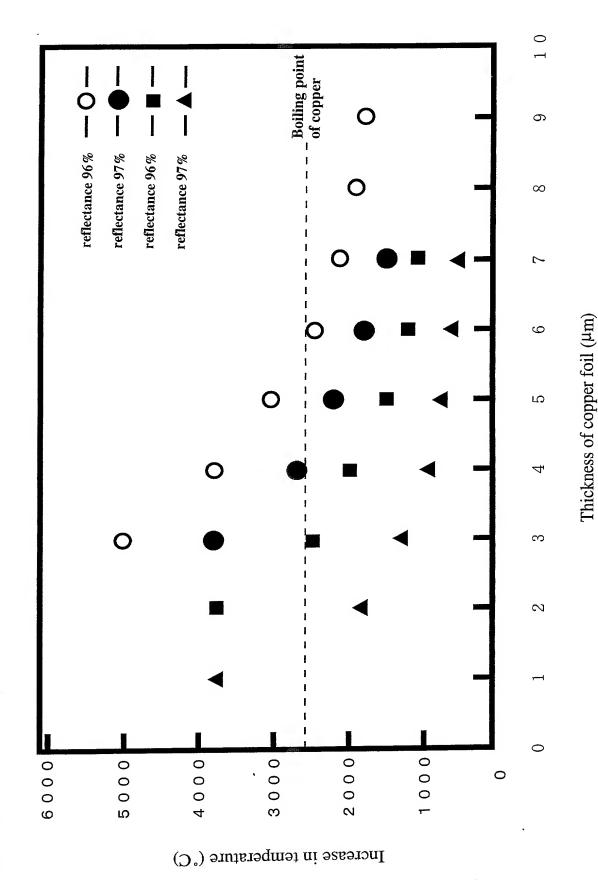


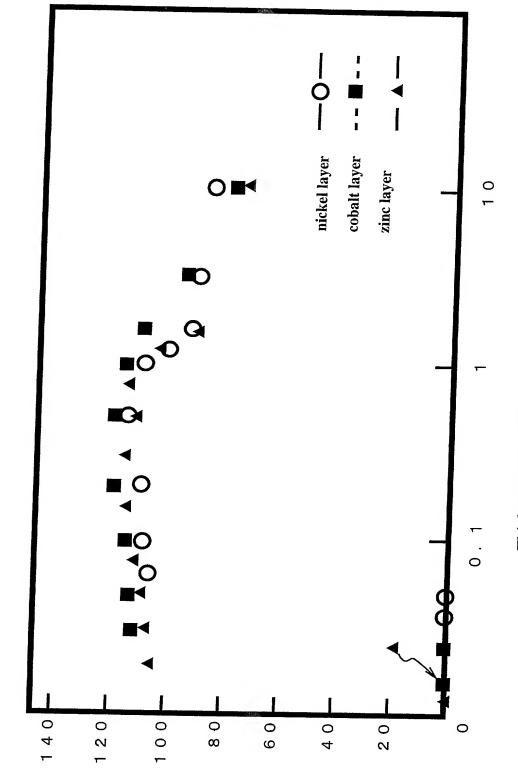
(h) Formation of a circuit through etching





-IG. 4



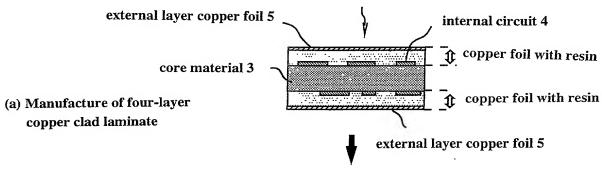


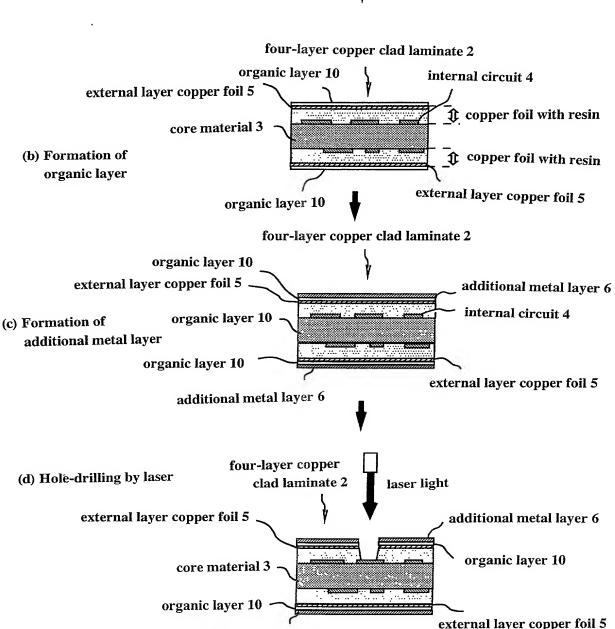
Diameter of a drilled hole  $\$   $\mu m$ 

Thickness of an additional metal layer /  $\mu m$ 

## FIG. 6

## four-layer copper clad laminate 2





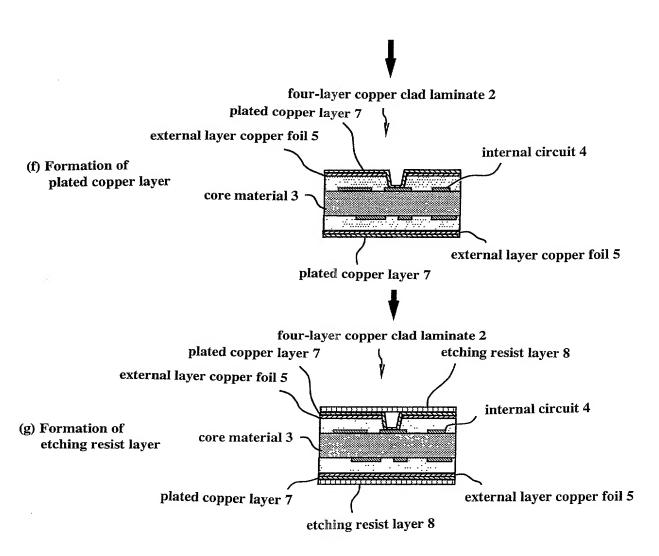
additional metal layer 6

four-layer copper clad laminate 2

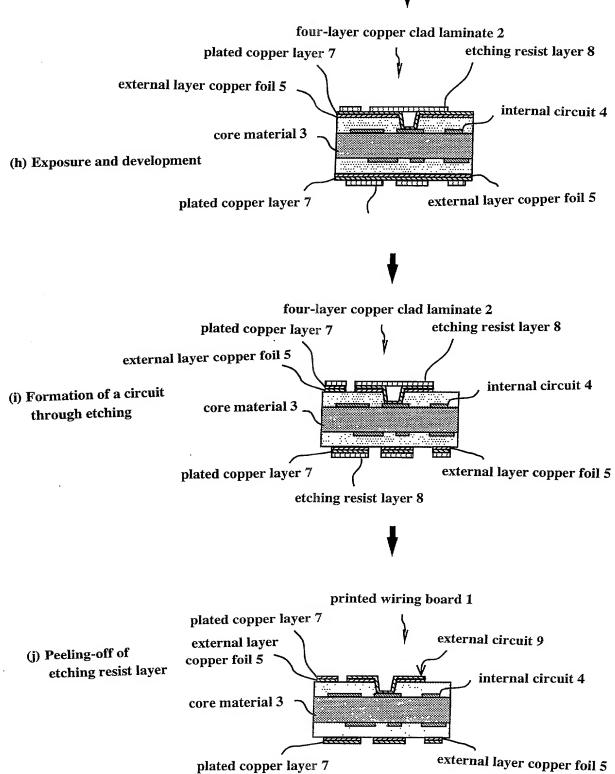
external layer copper foil 5

(e) Peeling-off of additional metal layer and organic layer core material 3

external layer copper foil 5







plated copper layer 7

Fig. 9

## four-layer copper clad laminate 2 external layer copper foil 5 core material 3 (a) Manufacture of four-layer copper clad laminate (b) Copper foil with resin external layer copper foil 5

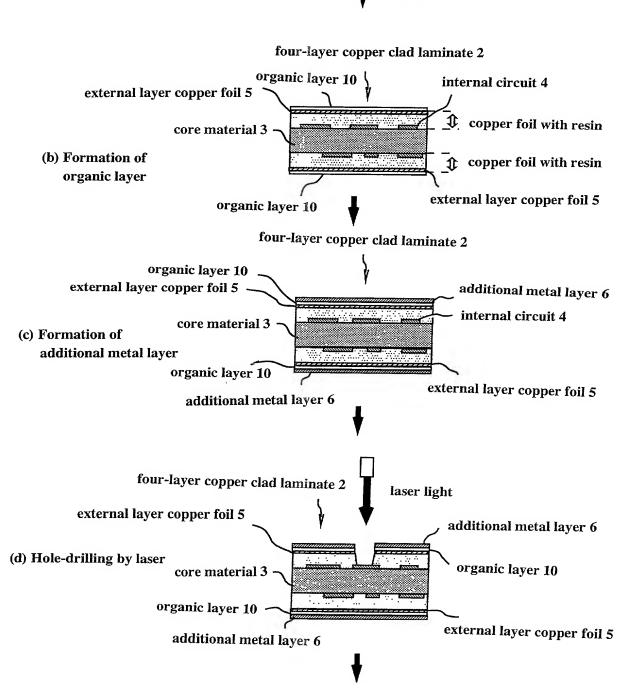
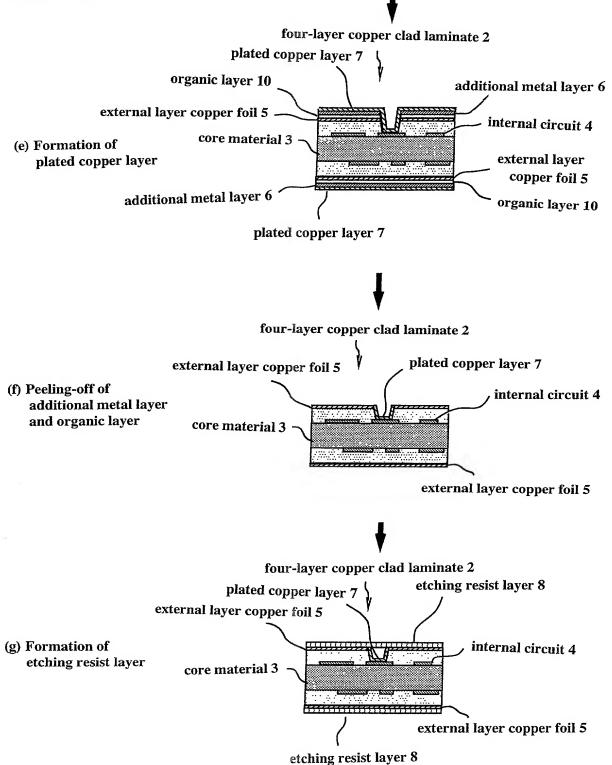


FIG. 10



## FIG. 11

